FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE TENT AND TRADEMARK OFFICE		ATTY, DOCKET NO.			SERIAL NO.	
(Use several sheets if necessary)				TI-37214			10/826,713	
<b>4</b>				APPLICANT: William D. Boyd				
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*EXAMIN	<u></u>			04/16/2004	1/16/2004		2826	
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*EXAMIN ER INITIAL	DOCUMENT NUMBER	DATE		NAME		SUBCLAS	S FILING DATE (IF APPROPRIAT	ľE)
RP5	US 6,784,539 B2	08/2004	Efland		257	712		
	US 6,597,065 B1	07/2003	Efland		257	712		
	US 6,683,380 B2	01/2004	Efland	et al.	257	734		
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	DOCUMENT NUMBER	DATE	DATE COUN		NAM	E	CLASS/SUBCLASS	
	OTHER DC	DCUMENTS a	Including Auth	por Title Date Per	rtinent Pages	Fic.)		
RXX	Appl. Serial Nun	nber 11/358,668	TI Docket	Number TI-3	9973 "Flig	Chip Pac	kage with Advance	èd l
Electrical and Thermal Properties for High Current Designs", William D. Boyd et al.								
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*EXAMINER: Initial in this form with next com	if reference considered, whether or not cita	ation is in conformance v	with MPEP 609;	Draw line through cits	ation if not in co	onformance and	not considered. Include cop	y of